

SiD Status and Plans

International Workshop on Linear Colliders
Morioka, 5 Dec 2016

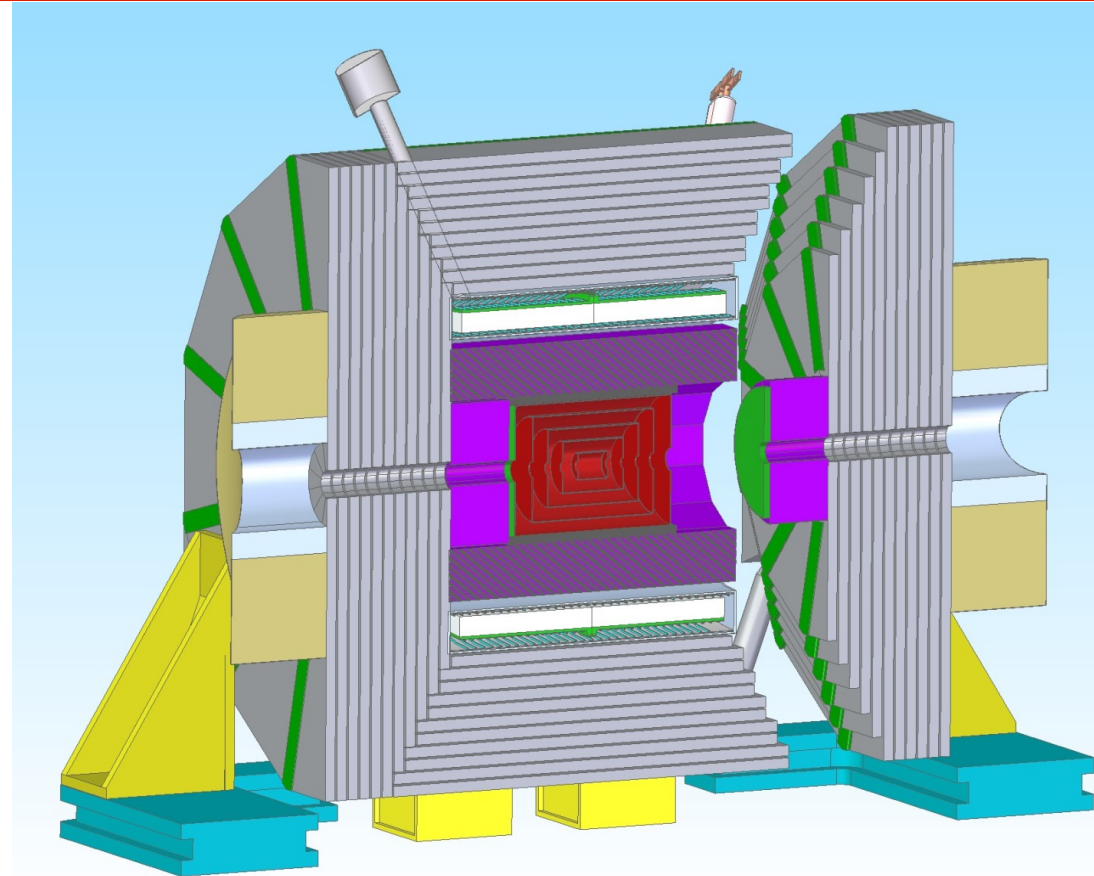


- ◆ Overview
- ◆ R&D and software developments
- ◆ Collaboration activities
- ◆ Outlook

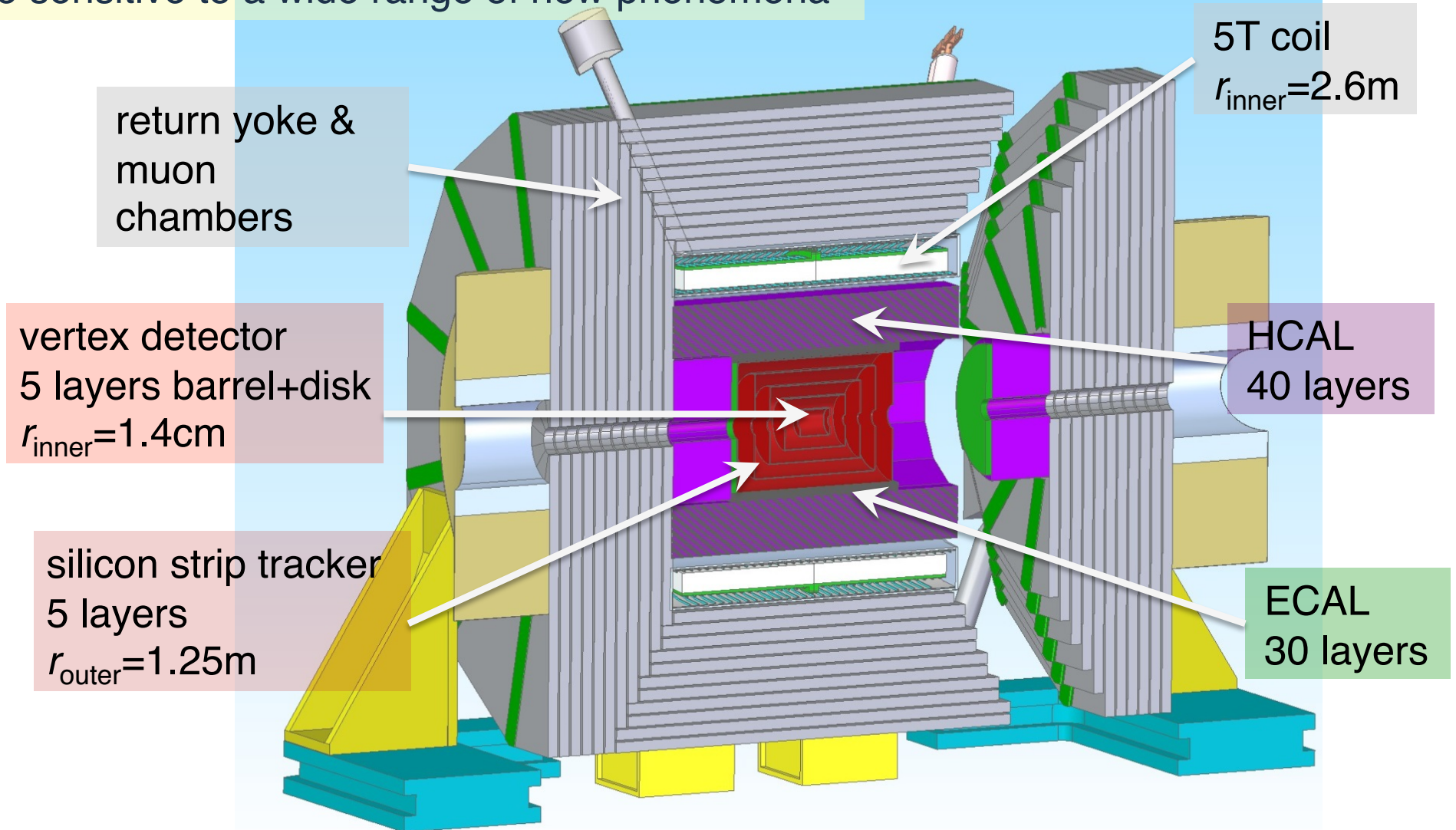
Aidan Robson
for the SiD Consortium



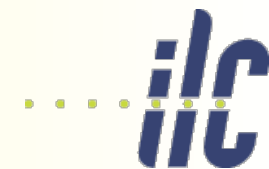
University of Glasgow | Experimental Particle Physics



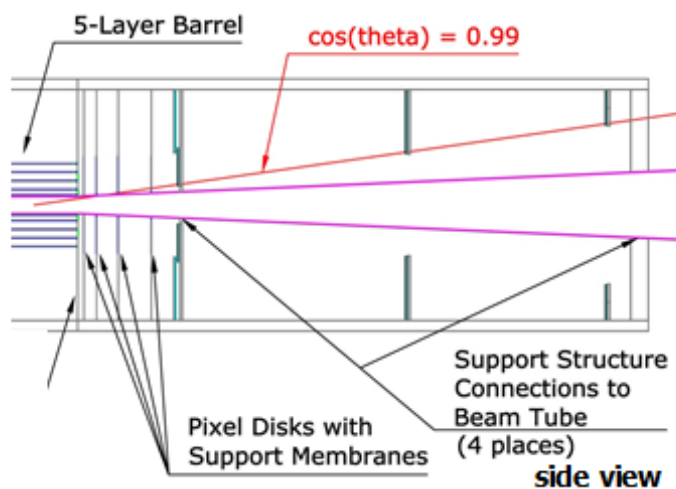
A compact, cost-constrained detector designed to make precision measurements and be sensitive to a wide range of new phenomena



SiD tracking



A robust, low-material, high-precision silicon system



Vertex Detector

Challenging requirements:

- $<3\mu\text{m}$ hit resolution
- Feature size $\sim 20\mu\text{m}$
- $\sim 0.1\%$ X_0 per layer material budget
- $<130\mu\text{W}/\text{mm}^2$
- Single-bunch timing resn

Technology choice comes later:

- Si diode pixels ('standard' tech)
- Monolithic designs (MAPS, Chronopix)
- Vertically integrated ('3d') approaches (VIP chip)
- High-Voltage CMOS

Silicon strip tracker

- Silicon microstrips, $25\mu\text{m}$ pitch / $50\mu\text{m}$ readout
- 5 barrel layers / 4 disks
- Tracking unified with vertex detector – 10 layers in barrel
- Gas-cooled
- Material budget $<20\%$ X_0 in active region
- Readout using KPiX ASIC bump-bonded to module

Baseline readout for SiD tracker and ECal is KPiX

R&D on CMOS monolithic front-ends

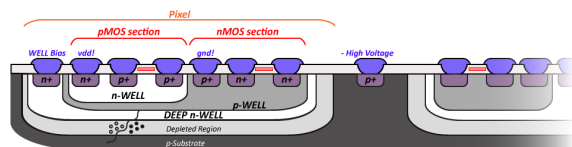
Integrate sensors and front-end electronics on the same substrate (CMOS monolithic approach)

Potential for:

- ◆ Lower material budget
- ◆ Smaller pixel size
- ◆ Lower costs

kPixM Test structure submission:

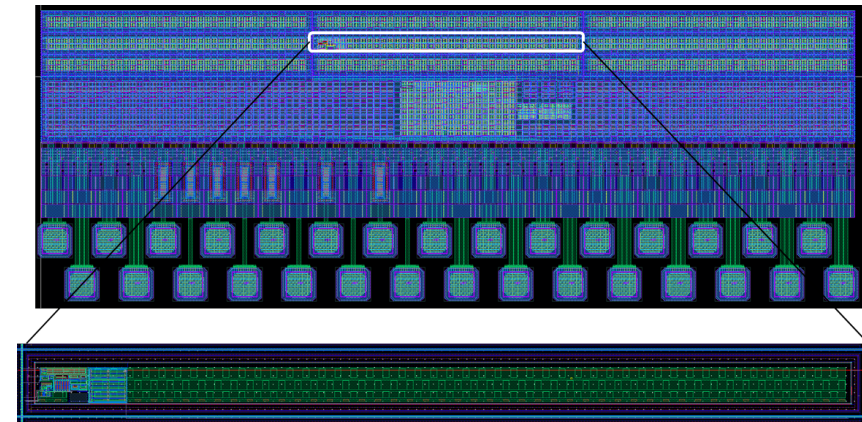
Technology LFoundry 150nm on high resistivity substrate (2kΩcm) thinned to 150μm (fully depleted with 80V)



- ◆ Passive pixels (40μm x 500μm)
- ◆ Active pixels (8 variants of 40μm x 500μm)
- ◆ Mosfet arrays for technology characterization

SLAC

	kPixM-Trk	kPixM-Cal
Pixel size Array	40x500 μm ² 200x2400	1000x1000 μm ² 100x94
Full Size	Stitched 5x5 reticles	Stitched 5x5 reticles
Max. Signal	1fC	1pC
Effective ENC	<200e ⁻	<1000e ⁻
Filtering	LP + CDS	LP + CDS
S/N	>20	>4
In pix mem. depth	1 bucket	16 buckets
ADC resolution	12 bits	12 bits
DC Power cons.	~ 20μW/pix	~ 20μW/pix
Power pulsing	Yes	Yes



◆ Series of three Chronopixel prototypes gave conclusions:

- ◆ Pixels can record time stamps with 300ns period
- ◆ All hit pixels can be read out between bunch trains (sparse readout)
- ◆ Pulsed power will not ruin comparator performance
- ◆ All NMOS electronics works with acceptable power consumption
 - Question remains: how well does it compare to deep P-well option?
- ◆ Comparator offset calibration works

◆ Many problems solved; concept proven valid

◆ Sensor diode capacitance an issue for 90nm process

Prototype 3 had six sensor options to study
 sensor diode capacitance:
 – large sensor capacitance in 90nm technology
 appears solved

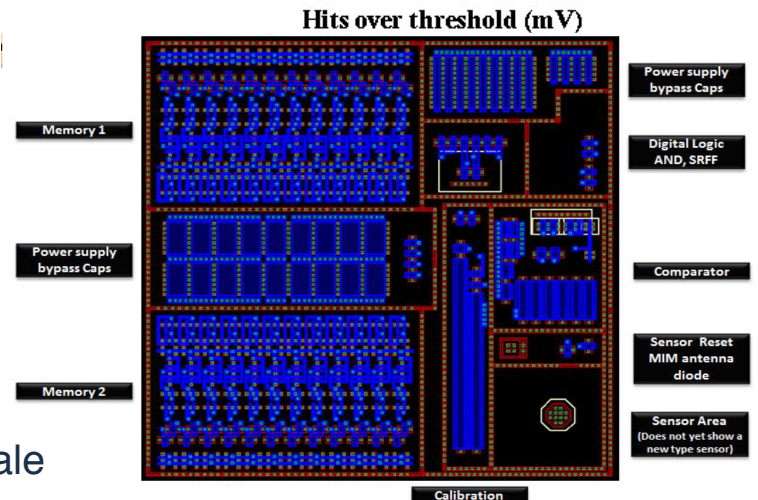
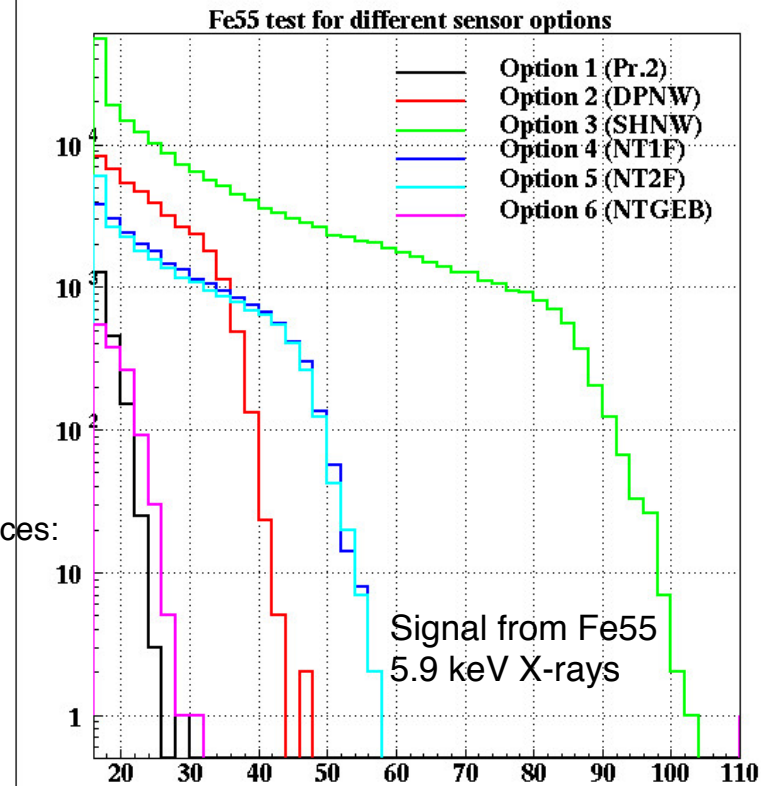
Derived capacitances:
 Opt 1 – 9.04 fF,
 Opt 2 – 6.2 fF,
 Opt 3 – 2.73 fF,
 Opt 4 & 5 4.9 fF,
 Opt 6 – 8.9 fF

◆ Need to fully understand sensor operation details, measure sensor efficiency for MIPs

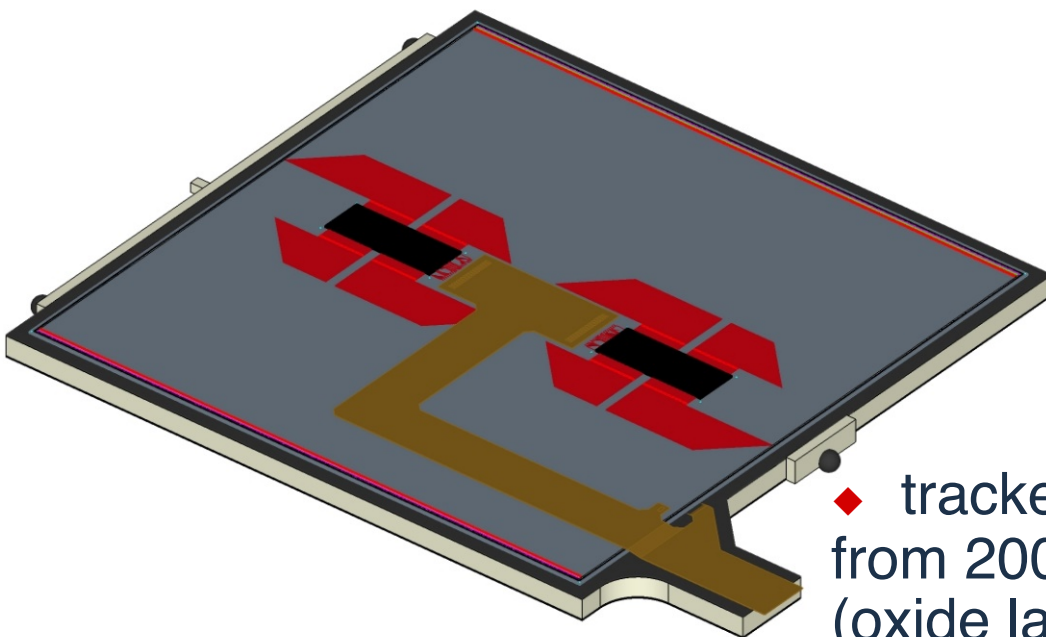
◆ Cross-talk issues have been addressed by separating analogue and digital power and adding small decoupling capacitor. Some minor cross-talk persists – will try to minimise more

◆ Measurements in progress at Yale with prototype 3 chips, including MIPs and rad-hardness

Oregon, Yale



Tracker sensors

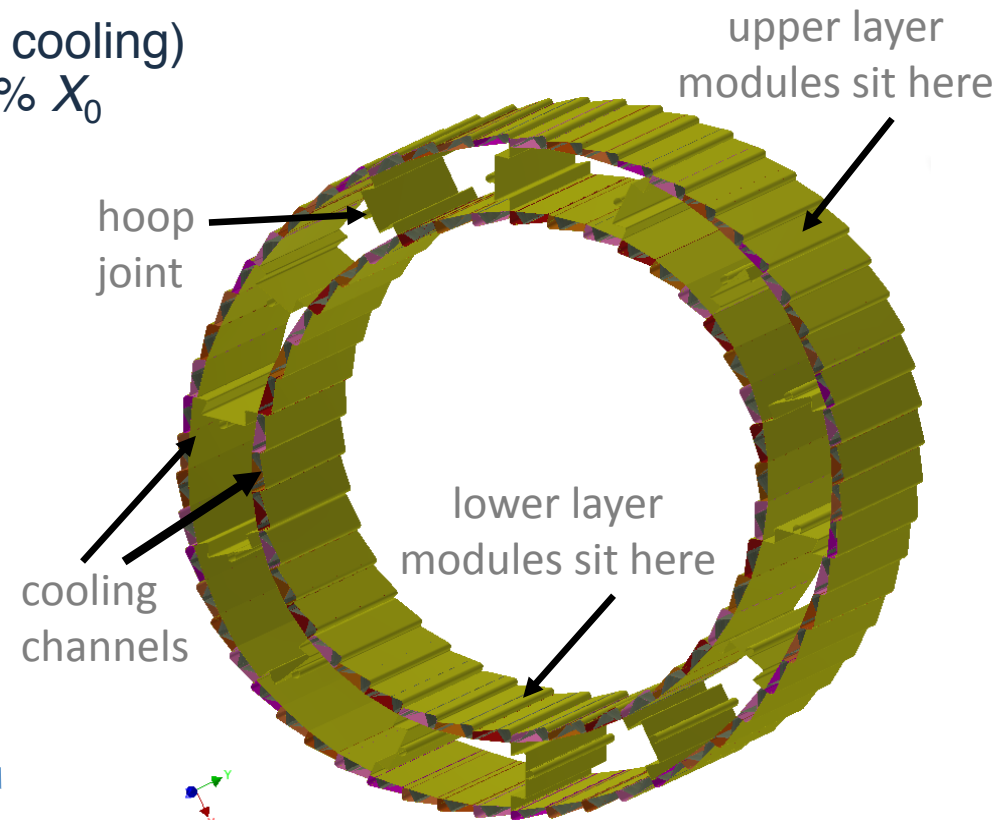


- ◆ tracker sensor prototypes from Hamamatsu from 2008 became damaged by wirebonding (oxide layer between Metal 1 and 2 inadequate)
- ◆ not pursued for several years
- ◆ renewed interest in 2016 (both SiD and ILD) and favourable negotiations with Hamamatsu; oxide layer thickness will be increased and Under Bump Metallization will be provided

Working towards full prototype test:
sensor + KPiX + cables

Tracker support structures

- ◆ Aim to build structures (including services and cooling) with lengths of several metres and less than 1% X_0
- ◆ Supports consist of CFRP box channels
 - ultra-high modulus skins
 - high moment of inertia
 - manageable dimensions
- ◆ Services are co-cured into the structure
- ◆ Also investigating possibilities for linking the box channels



Modules on top and bottom for two strip system adjacent layers

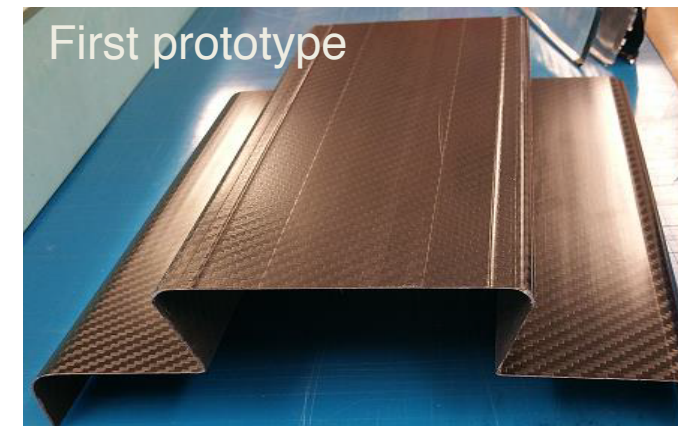
2-3m

20-30cm

Tongue-and-groove for possible linking to next channel

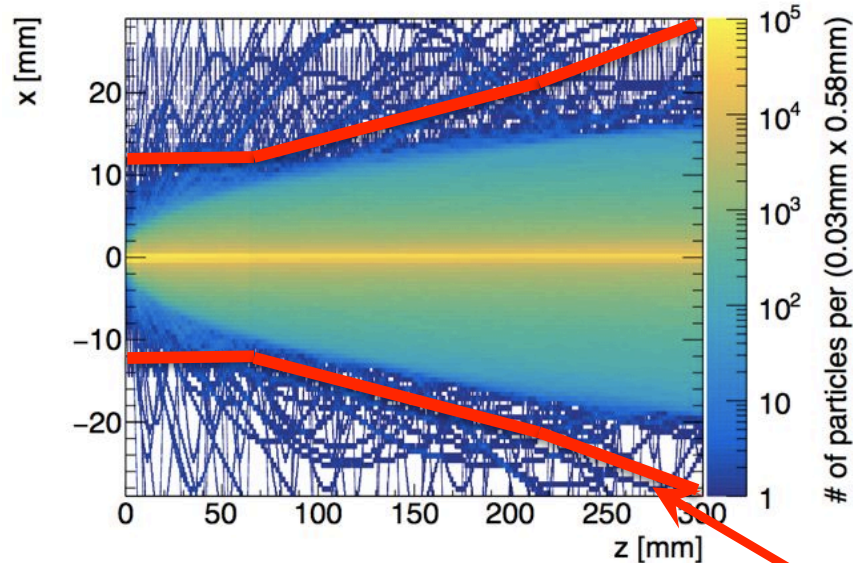
FEA studies done

U of Oxford, U of Lancaster



Pair background envelope

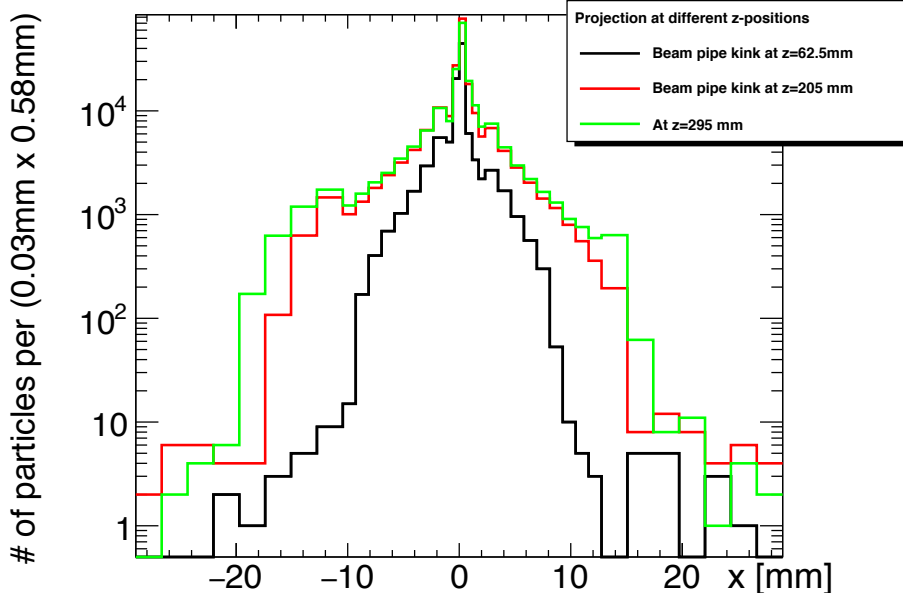
Pairs spiraling in the magnetic field



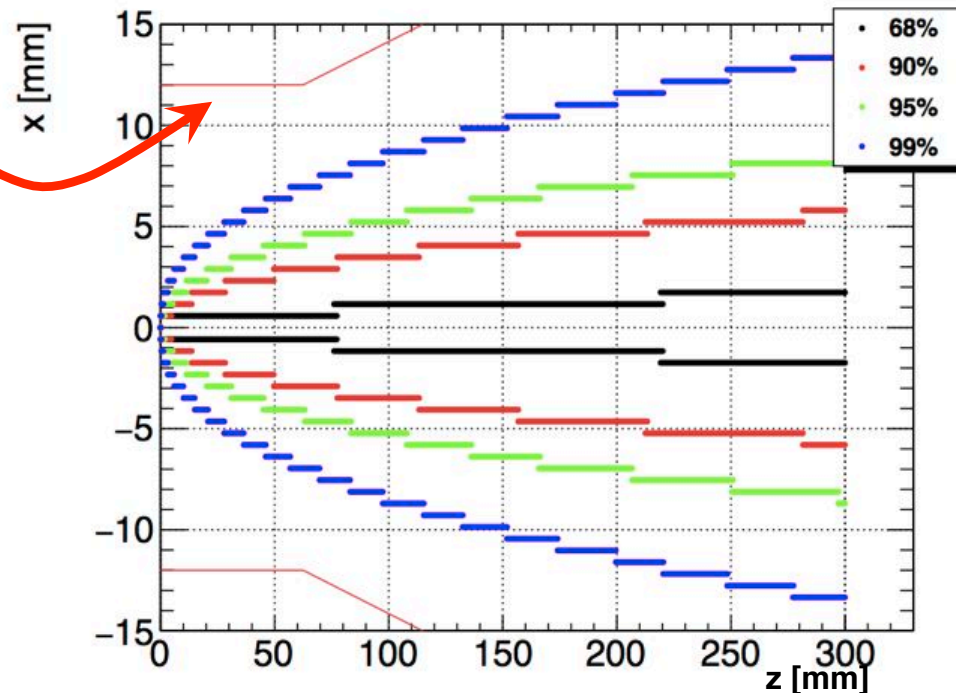
Re-analysed pair background envelope in beam pipe

- ◆ with current beam pipe design, around 0.45% of all particles leave tracks outside the beam pipe
- ◆ could consider reducing beam pipe radius by 2mm
- ◆ could consider an additional vertex detector layer for SiD at $r=7$ mm

Pairs spiraling in the magnetic field

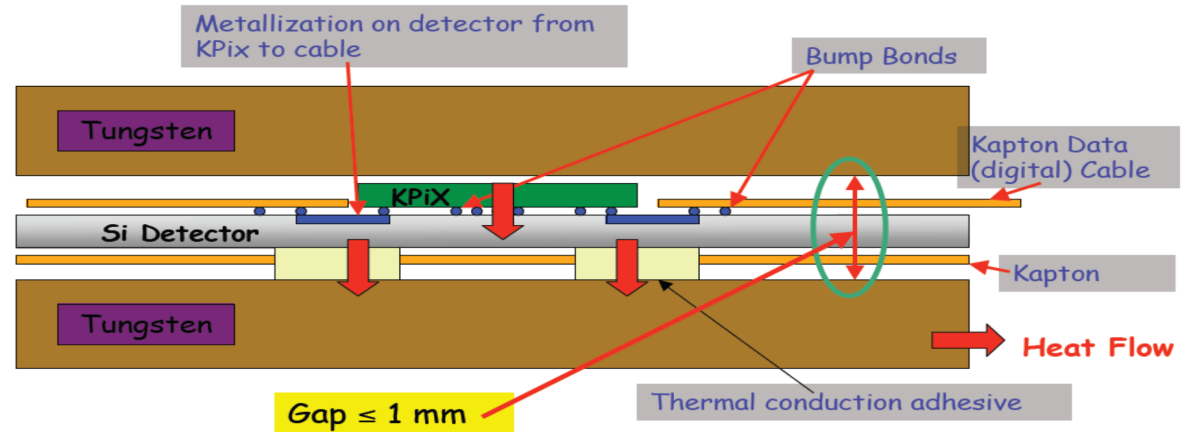


Envelopes outlining fractions of helix tracks from pair backgrounds

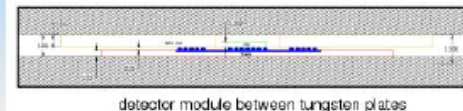
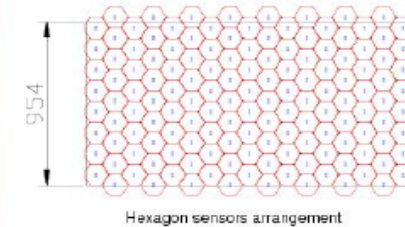
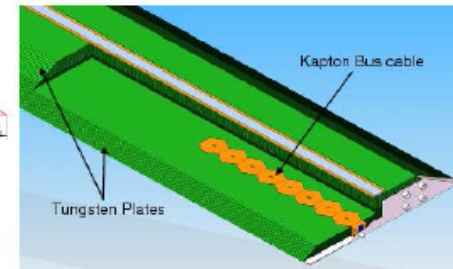
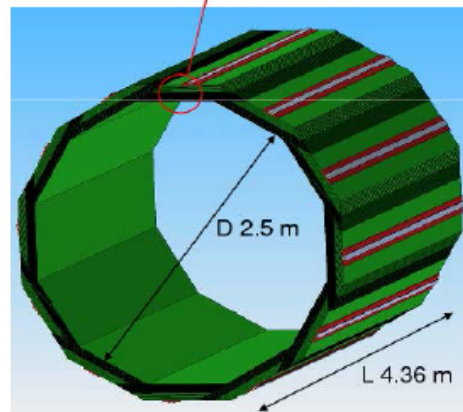
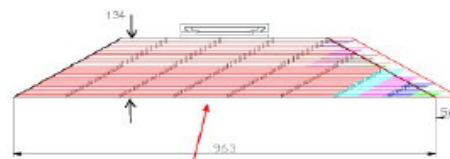
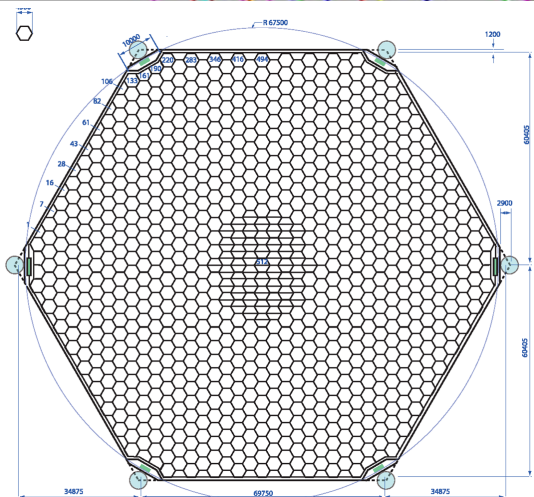
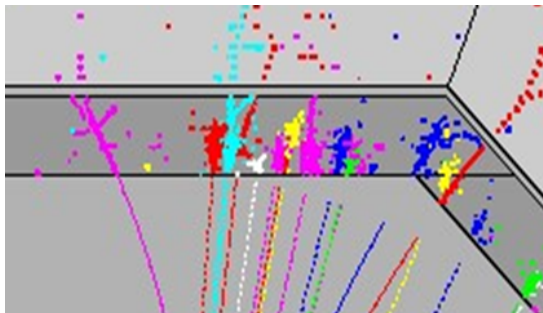


Highly granular 'imaging' calorimetry essential for ILC physics programme:

- ◆ Particle ID/reconstruction
- ◆ Tracking charged particles
- ◆ Integral part of Particle Flow detector design



- ◆ Baseline design: silicon / tungsten



Baseline configuration:

- transverse: 12 mm^2 pixels
- longitudinal: $(20 \times 5/7 X_0) + (10 \times 10/7 X_0) \Rightarrow 17\%/ \sqrt{E}$
- 1 mm readout gaps \Rightarrow 13 mm effective Moliere radius

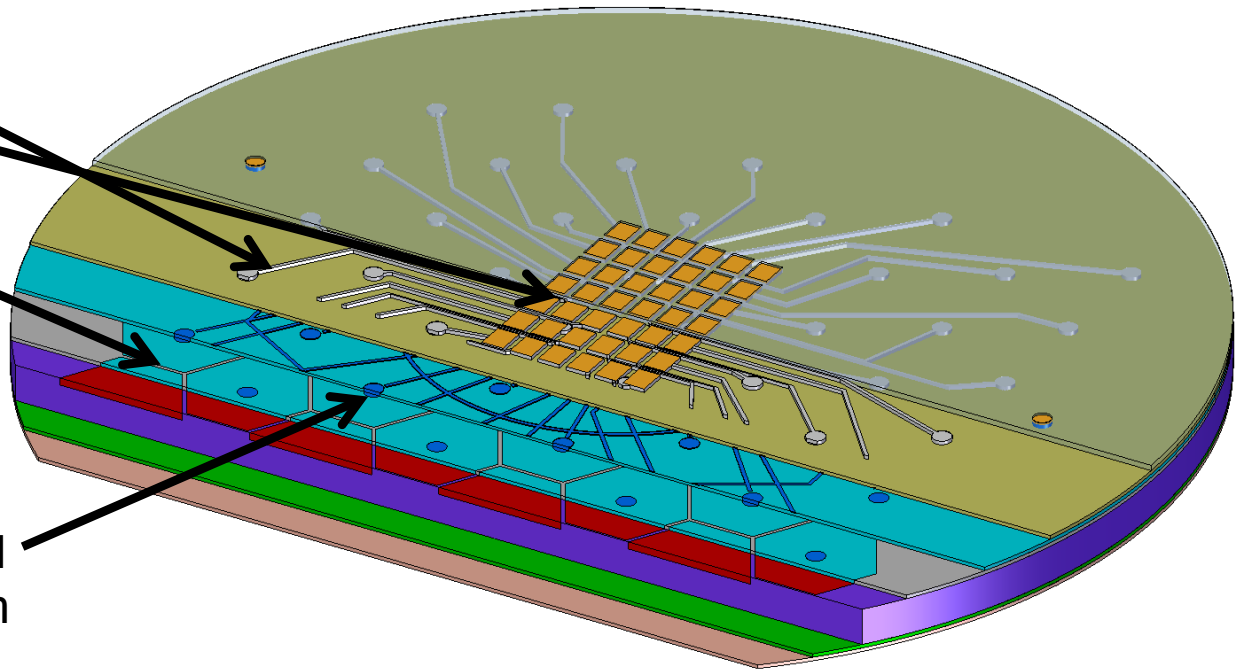
ECal sensors

Major lessons so far....:

- ◆ Bump bonding to sensors with Al pads can be very difficult
 - sensor foundry build final pad stack – Under Bump Metallization
- ◆ Sensors with ROCs can have issues with parasitic couplings
 - shield pixel traces

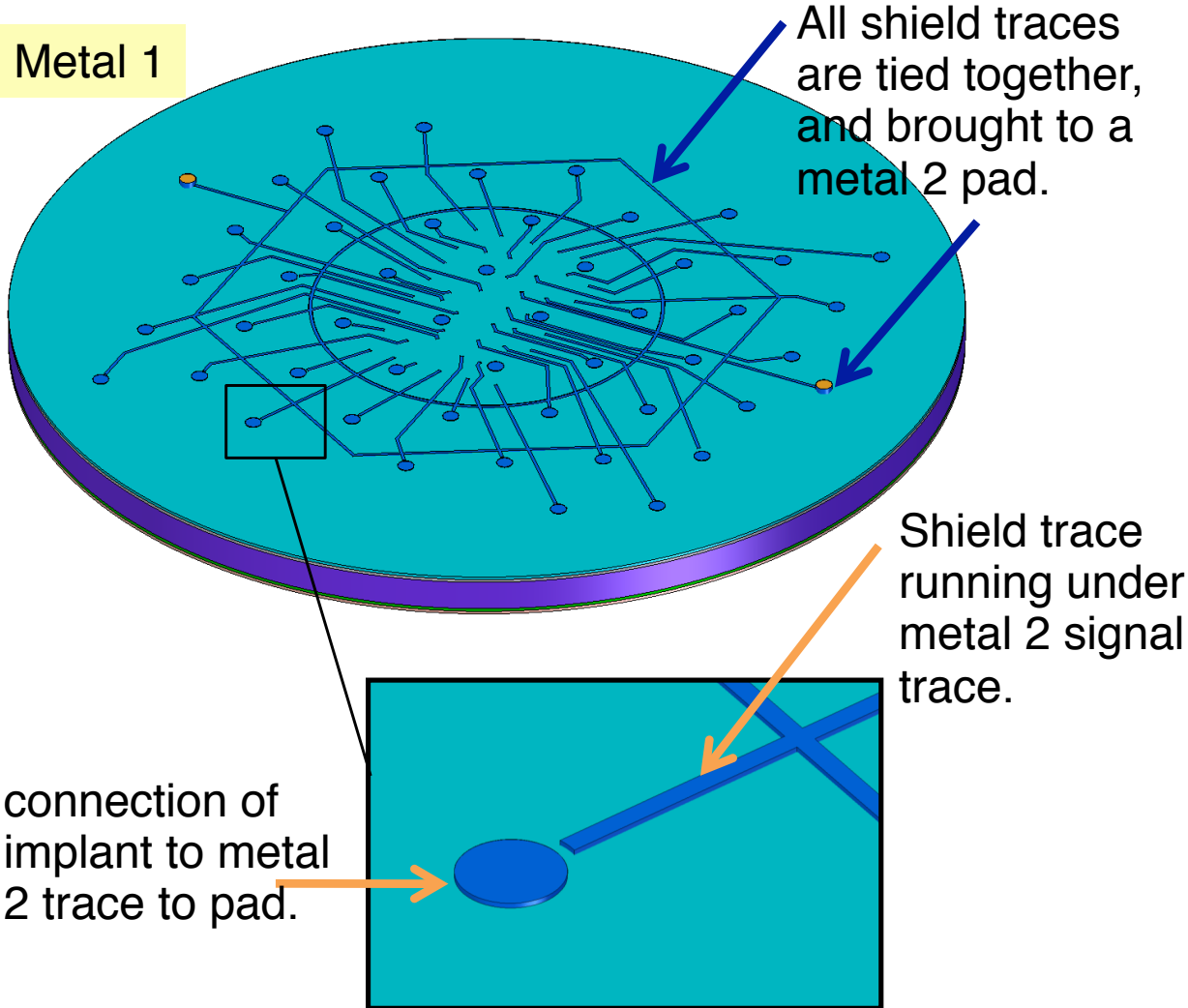
In present design, metal 2 traces from pixels to pad array run over other pixels: parasitic capacitances cause crosstalk.

New scheme has “same” metal 2 traces, but a fixed potential metal 1 trace shields the signal traces from the pixels.

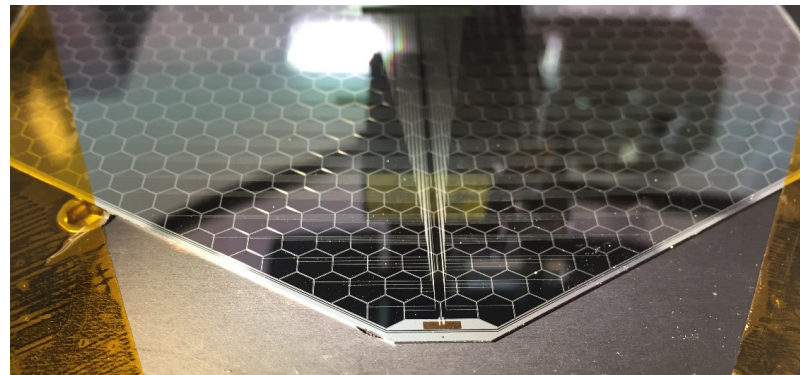
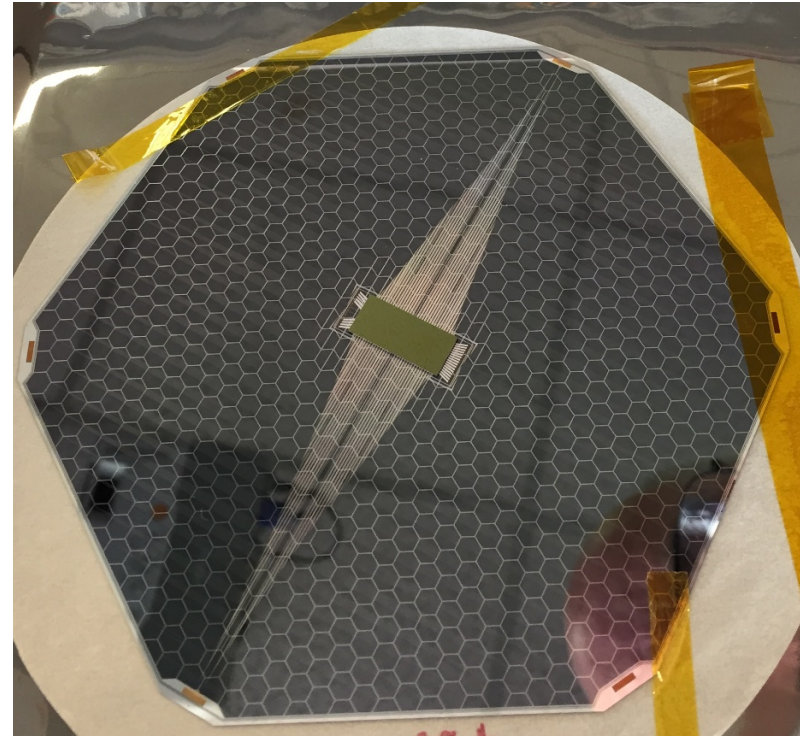


ECal sensors

Metal 1

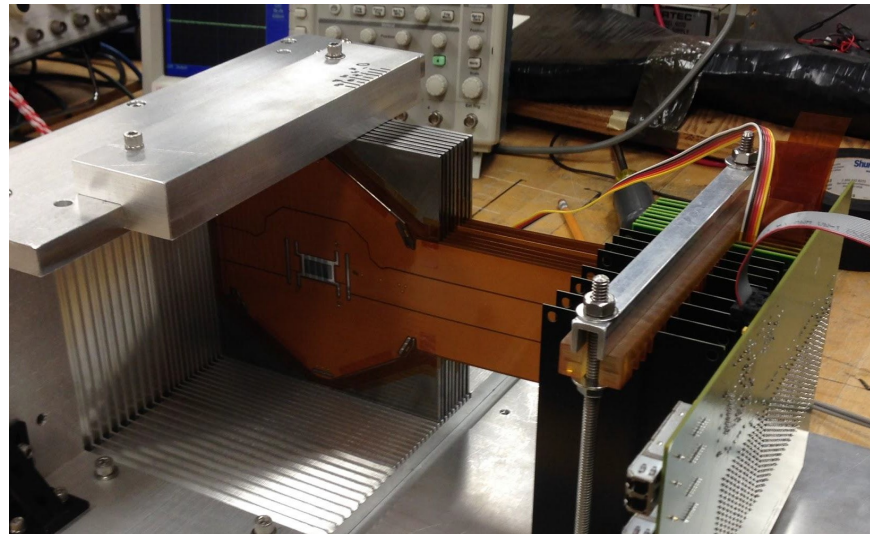
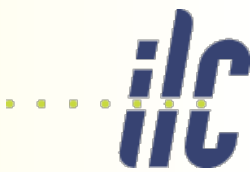


New prototypes with KPiX attached

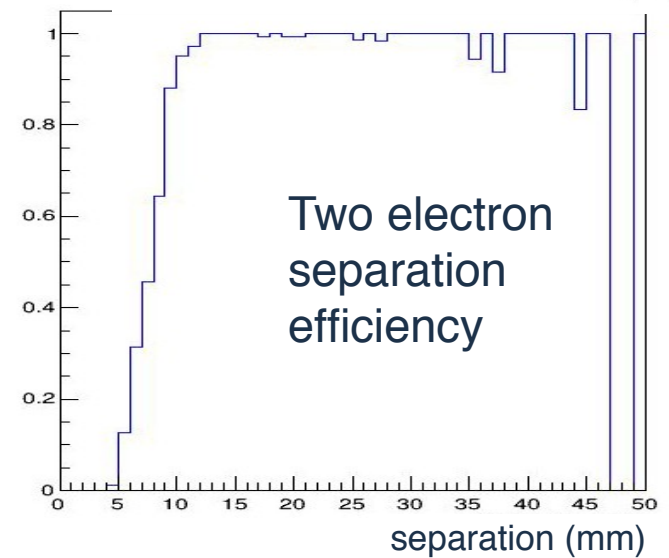
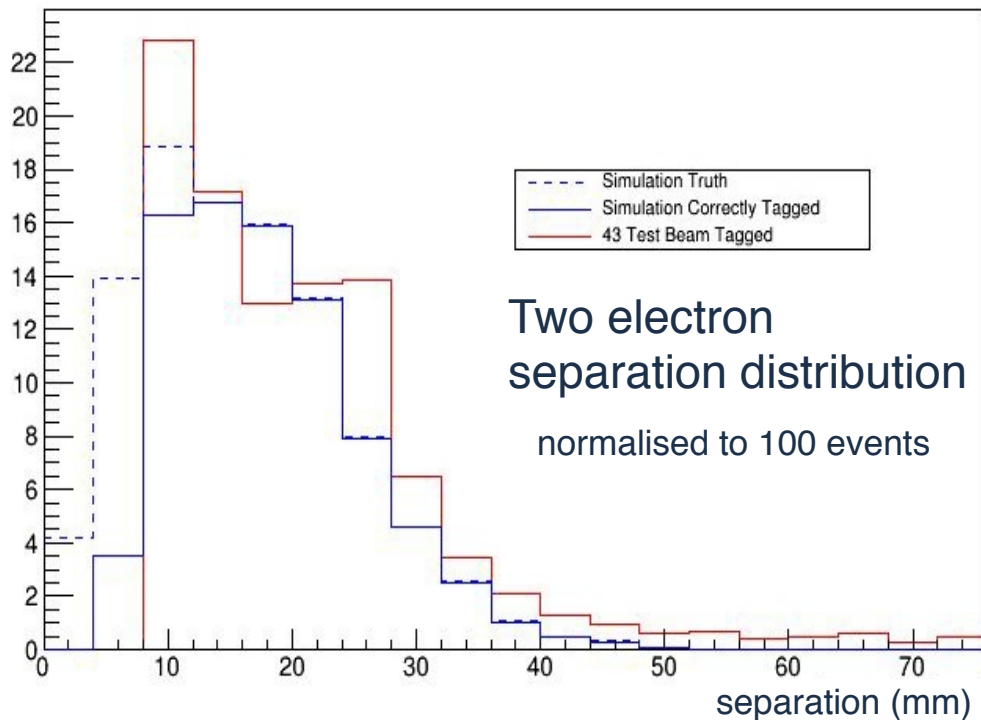
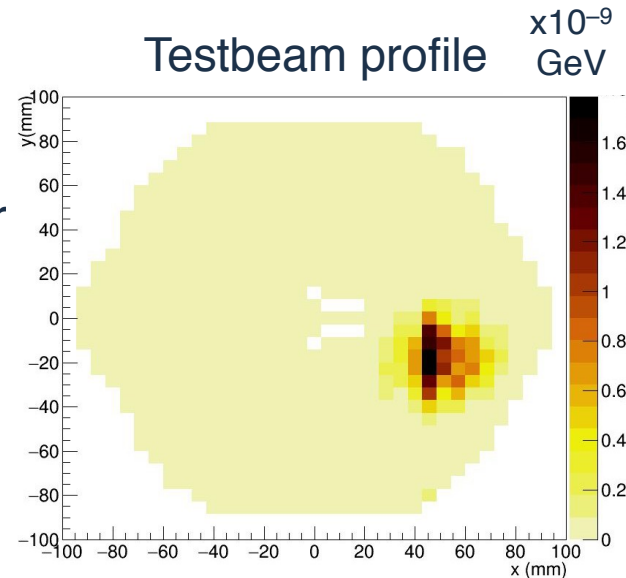


Testing underway, preparing for cable attachment →

SiW ECal testbeam analysis



- ◆ 9-layer Si/W calorimeter
- ◆ $\sim 6X_0$
- ◆ 13mm^2 pixels
- ◆ 12.1 GeV electrons

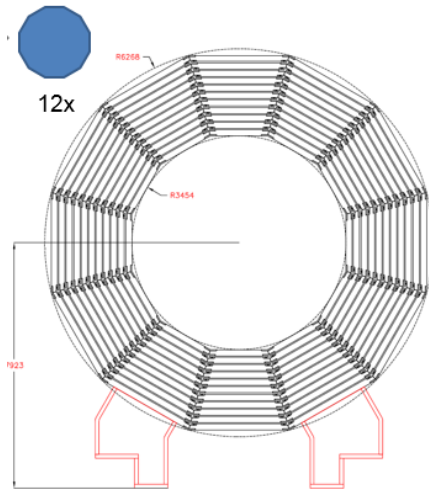


U of Oregon, SLAC, UC Davis

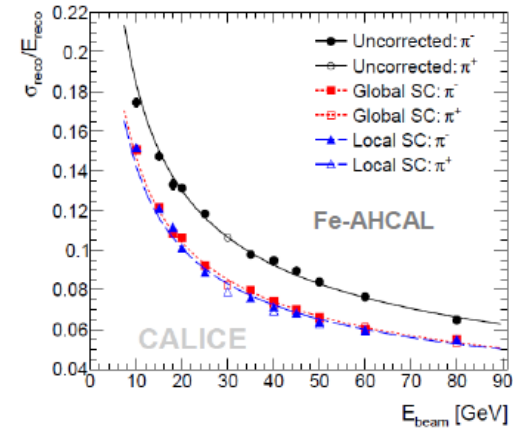
-> See talk by A. Steinhebel in Cal session

HCal

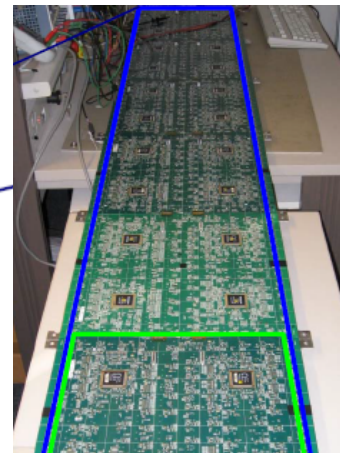
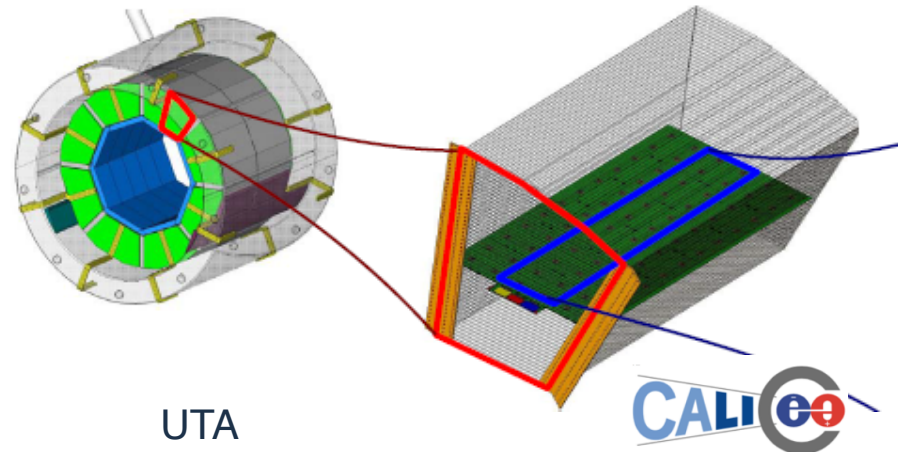
Following a review, new baseline technology for the SiD HCal is Scintillator / SiPM / Steel



Work ongoing to compare simulated single-particle energy resolution with CALICE testbeam results



Mechanical design following rebaselining



UTA

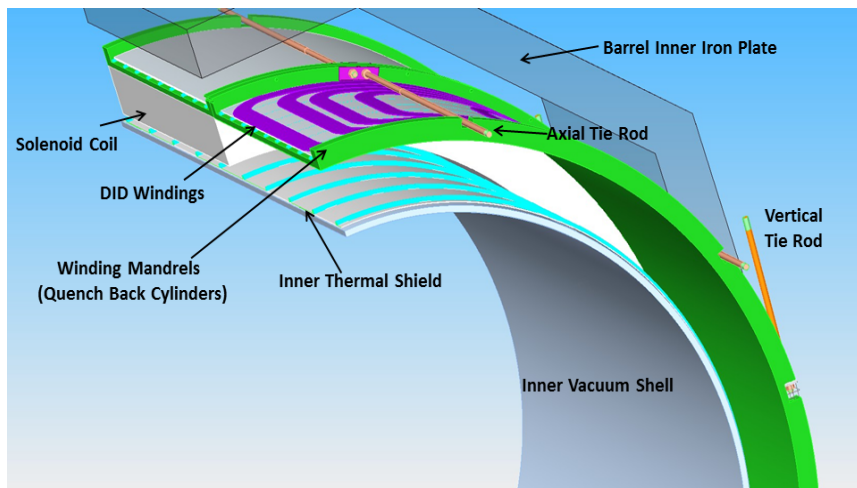


Steel 19mm	
Air 2.0 mm	Top plate 0.5 mm
Copper 0.068 mm	Polyimide foil 0.115 mm
PCB 1.0mm	Reflector foil 0.1 mm
Scintillator 3.0mm	Reflector foil 0.1 mm
Bottom plate 0.5 mm	
Steel 19mm	

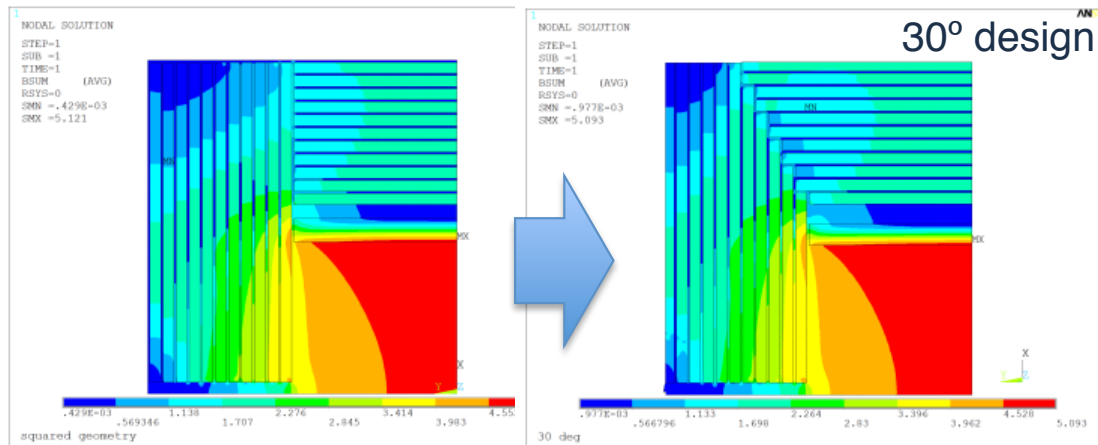
Active layer thickness = 7.383 mm

Solenoid

5T field

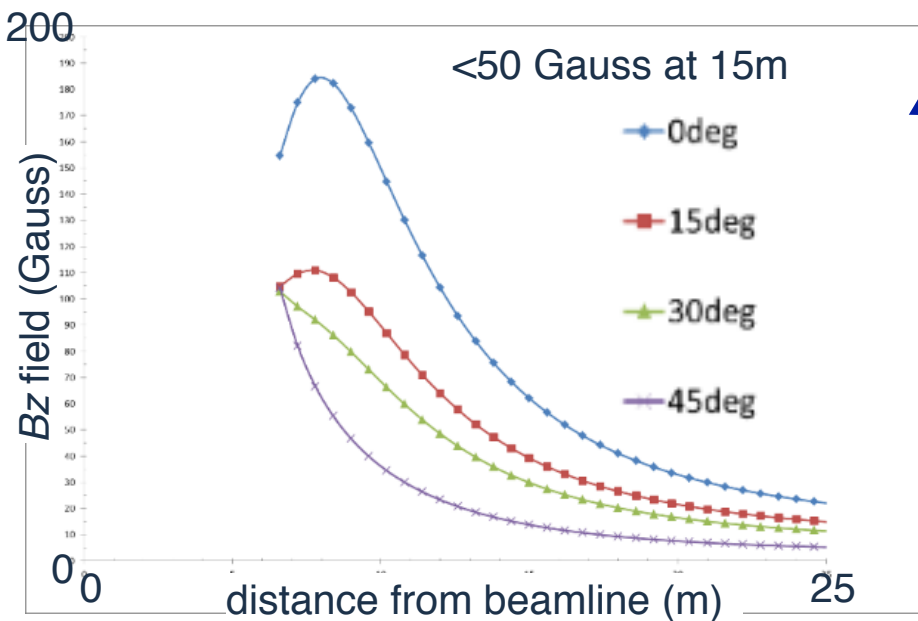


Baseline CMS conductor

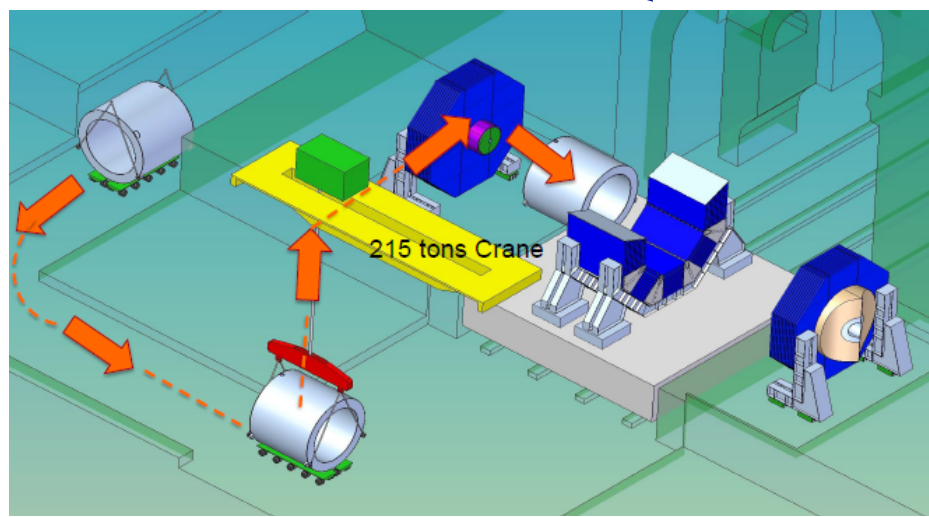


Recent redesign of barrel / door junction:

- ◆ More efficient flux return
- ◆ Easier transport / handling



SLAC

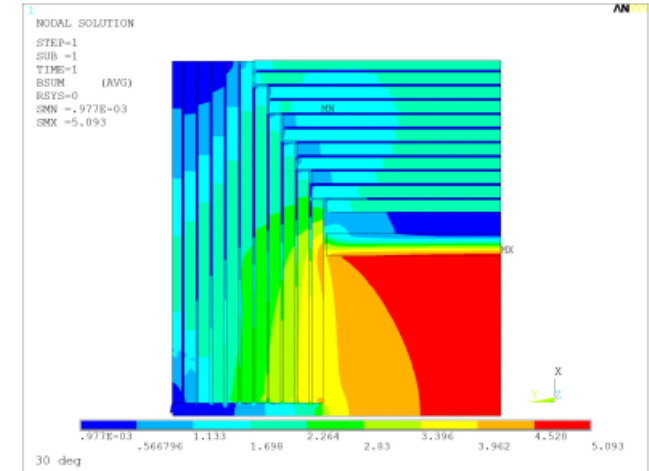
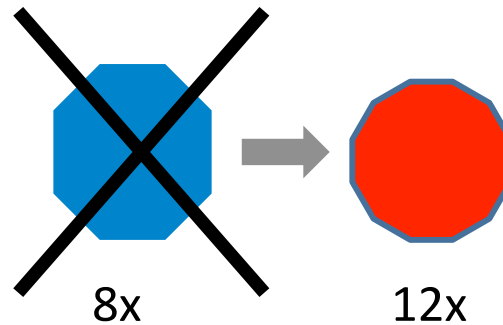


Muon identifier / calorimeter tail catcher

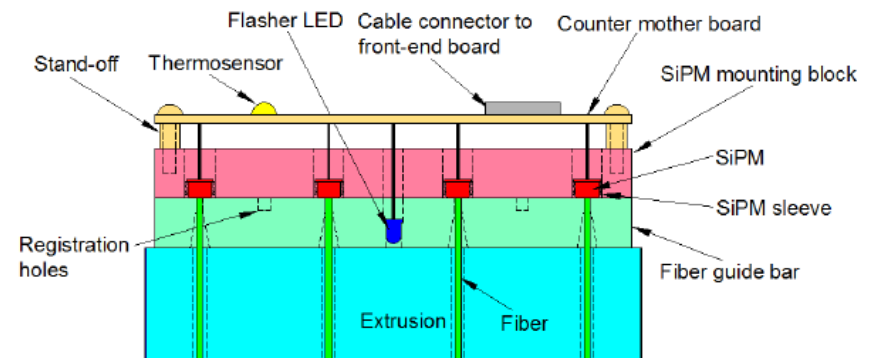
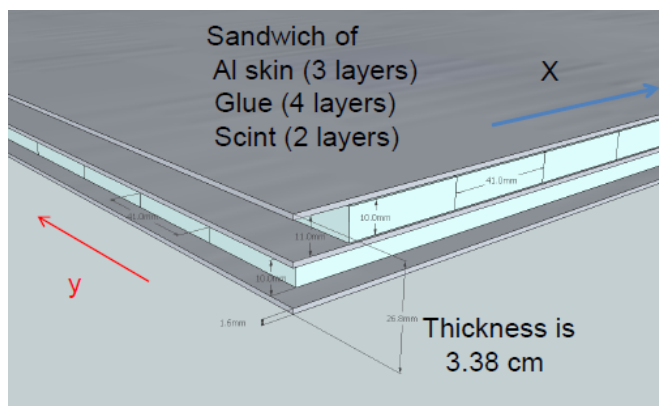
SiD baseline: long scintillator strips with WLS fibre and SiPM readout



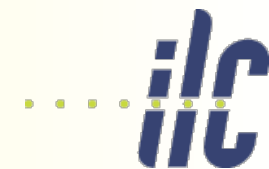
Yoke/Muon system changes since DBD:



- ◆ Consistent extension of the baseline HCal scintillator technology
- ◆ Need to optimize number of layers, strip dimensions



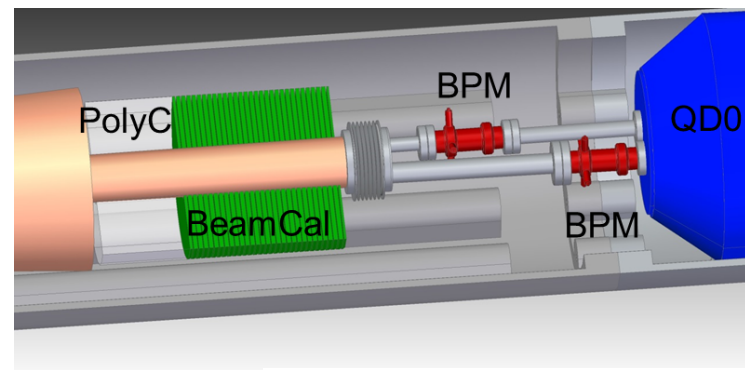
Forward region layout



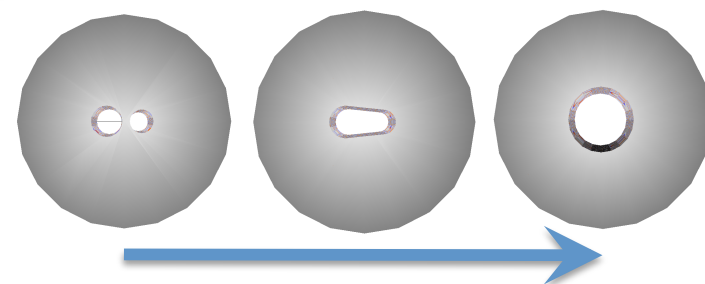
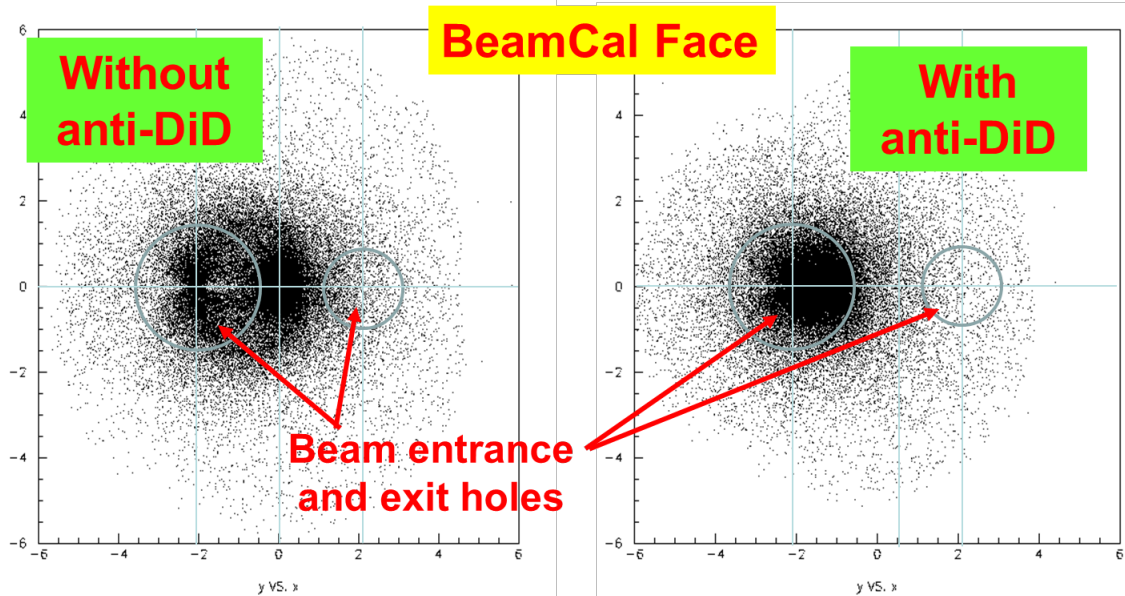
Recent studies have looked at different aspects of the forward region layout

Set of related questions:

- ◆ Is the anti-DiD necessary?
- ◆ What is the optimum forward calorimeter (BeamCal) shape?
- ◆ What buffer depth is required for forward/inner detectors?



DID: Detector-integrated Dipole

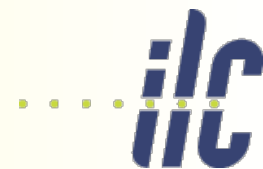


More aggressive approach to removing material from the path of backgrounds

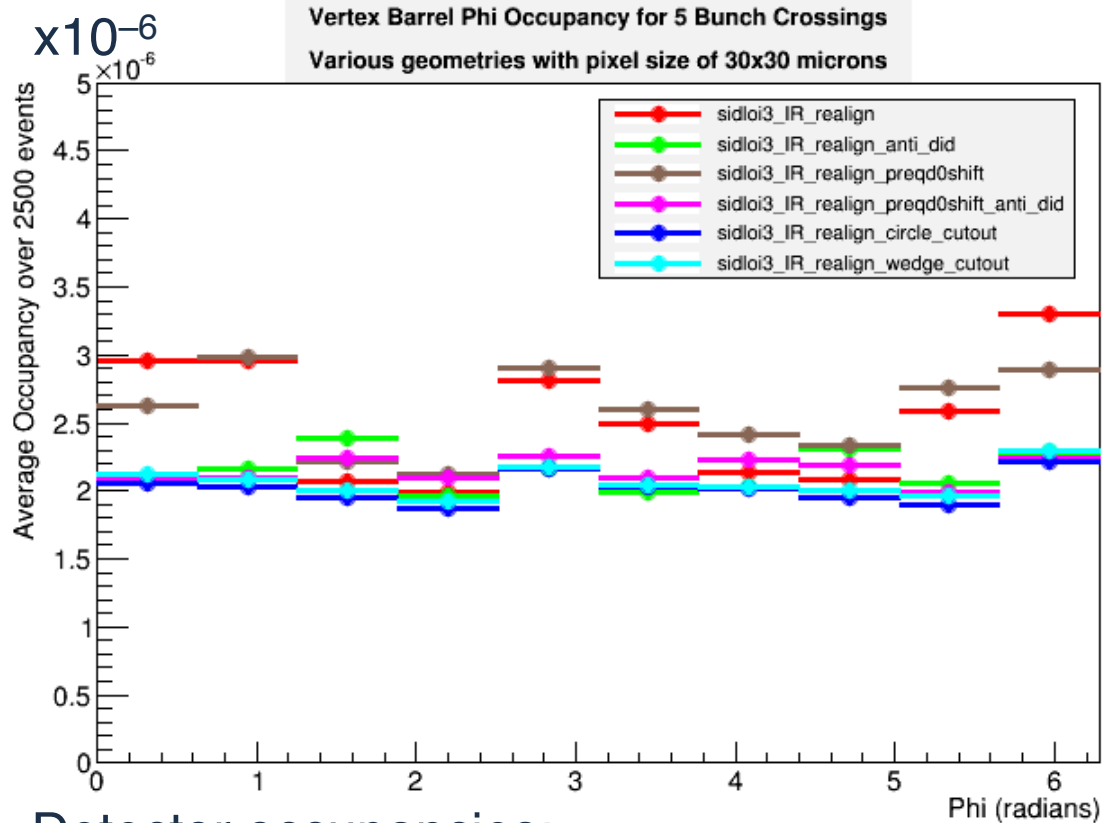
Trade-off between BeamCal reconstruction efficiency and albedo effect

UCSC, SLAC

Vertex detector occupancy



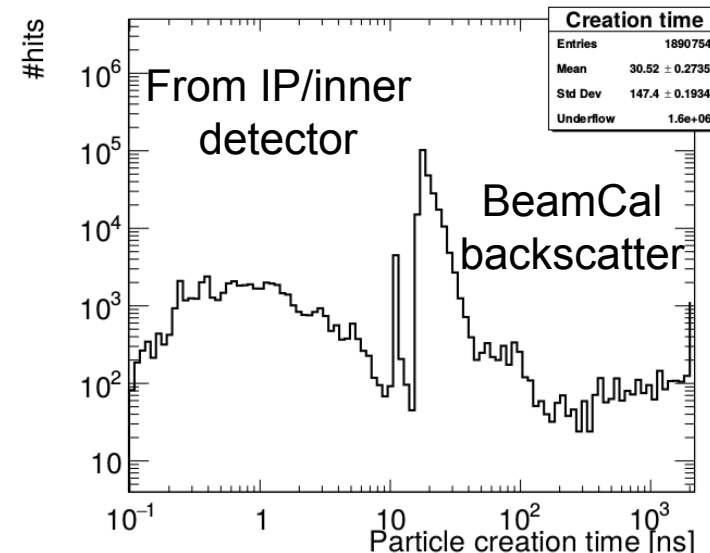
Forward region design can affect vertex detector occupancy:



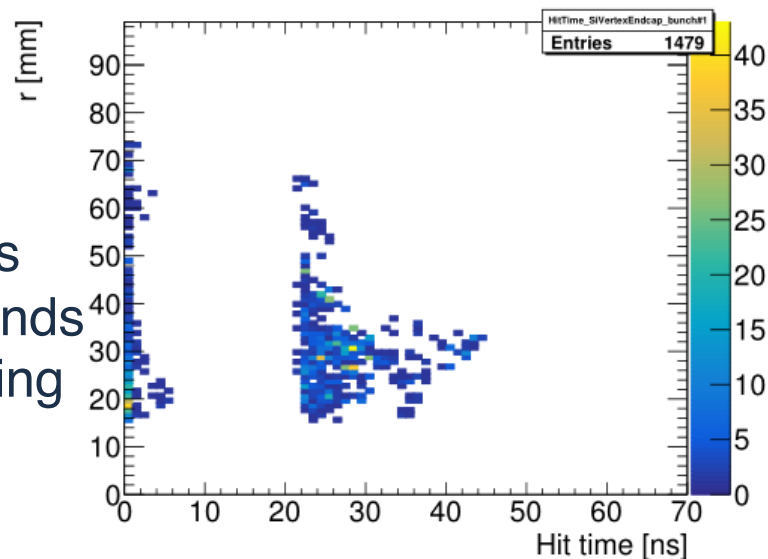
Detector occupancies:
with/without anti-DID
different beam holes
-> robust

Background pairs hits
can arrive microseconds
after the beam crossing
-> able to reject with
timing cuts

Creation time of particles hitting subdetector SiVertexEndcap

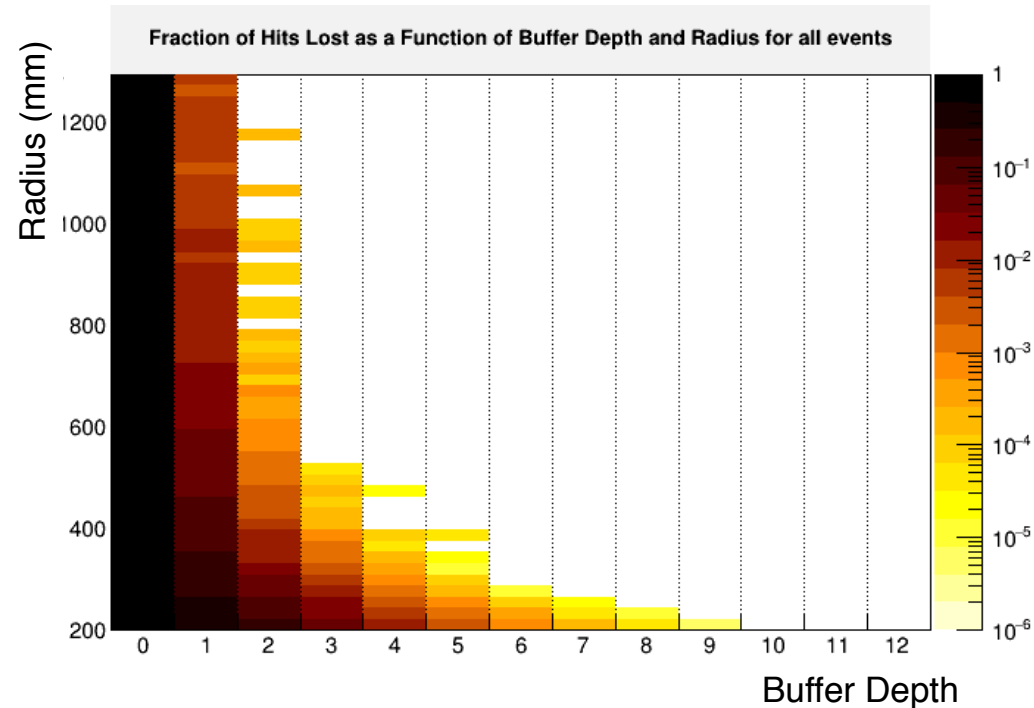
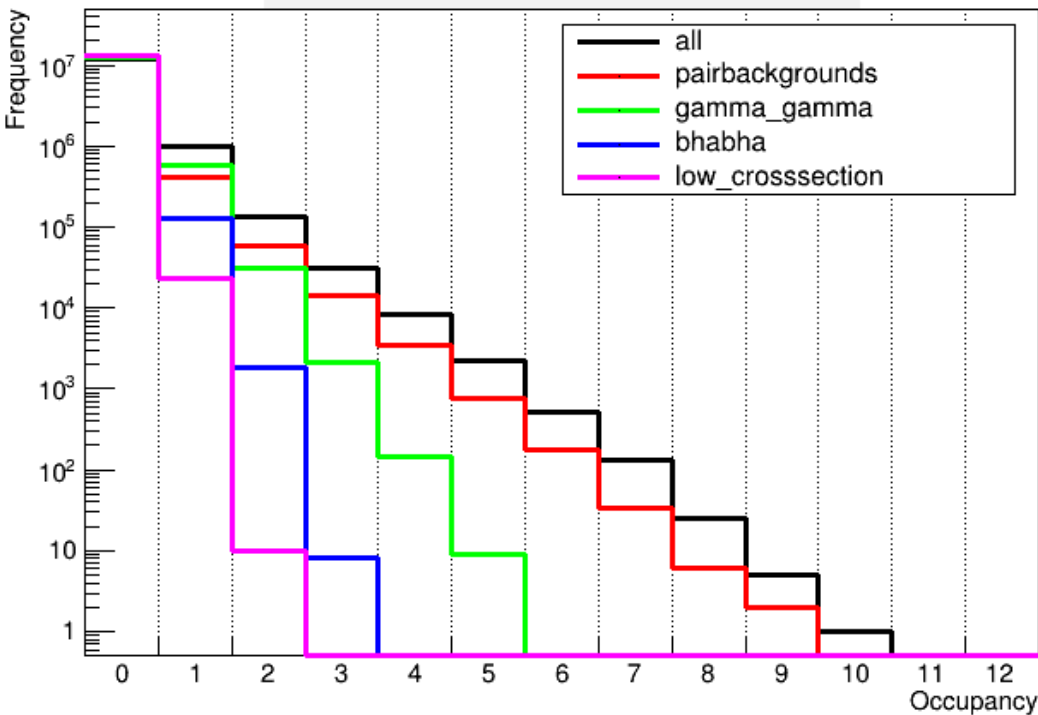


Radial position of hits over hit time, SiVertexEndcap



Forward calorimeter buffer size

Forward Electromagnetic Calorimeter Occupancy



Detailed study of dominant low-angle backgrounds
using latest beam parameters

Many channels in forward ECal have ~ 10 hits per train

Depth of 4 buffers \rightarrow lose around 10^{-3} of hits

Depth of 6 buffers \rightarrow lose around 10^{-4}

\rightarrow need 8 buffers to maintain losses below 10^{-4} for innermost radii

add arXiv number

UCSC

Beam-related muon background

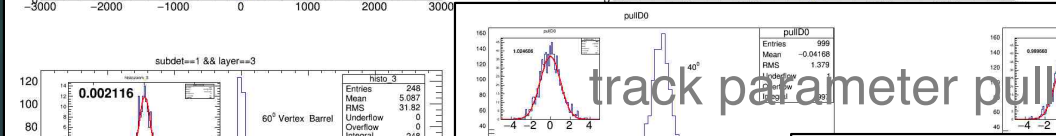
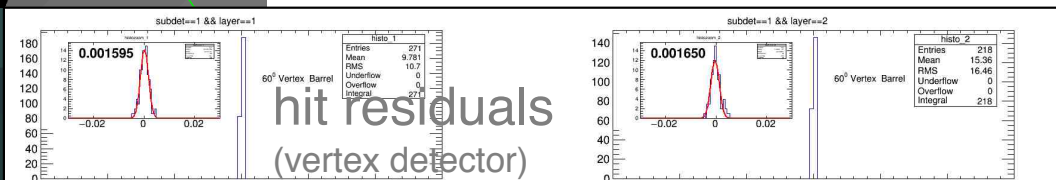
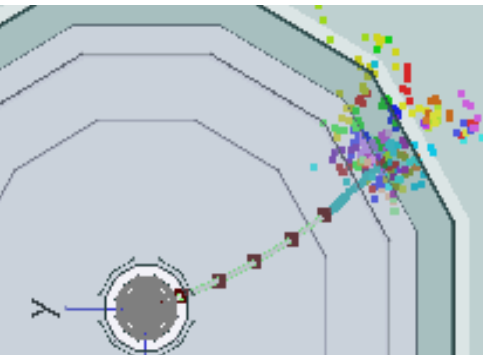
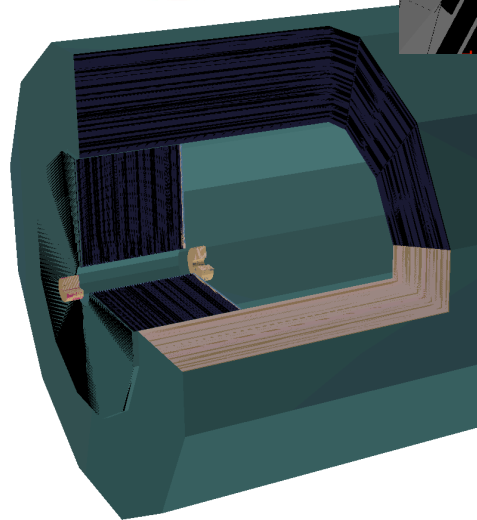
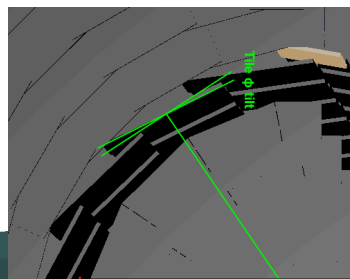
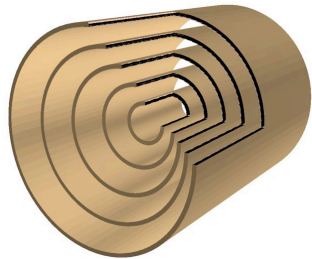
Add?

Simulation & reconstruction



At LCWS15, SiD decided to implement DD4HEP simulation and common reco

- ◆ Implemented geometry and drivers
- ◆ Updated to latest digitizers
- ◆ Developing performance benchmarking tools
- ◆ Currently commissioning full CLIC-style pattern recognition and Pandora PFA



Relies on close collaboration/support from CLICdp and ILD developers



-> See talk by B. Mishchenko in Sim/Reco/Perf session

Glasgow, UTA, Oregon, UCSC

Z pole running



add alignment/Z pole running summary and pointer to dedicated session

Collaboration activities



Excellent SiD software/optimization workshop at PNNL in September

NEWSLINE

THE NEWSLETTER OF THE LINEAR COLLIDER COMMUNITY

CURRENT ISSUE
3 NOVEMBER 2016

Calorimeter under
telescope scrutiny

Strasbourg steers ILC
towards ESRFI roadmap

Construction completed:
ILC in Roppongi

Download the current issue
as a full .pdf

ANNOUNCEMENTS

LCWS2016 early registration
deadline extended

The early registration deadline
for LCWS2016 in Morioka,
Japan, has been extended to 7
November.

CALENDAR

Upcoming Events

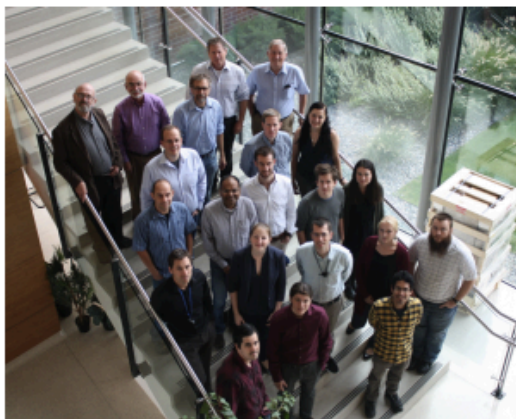
International Workshop on
Future Linear Colliders

FEATURE

SiD optimisation group moves towards new detector model after PNNL meeting



Jan Strube, PNNL | 20 October 2016



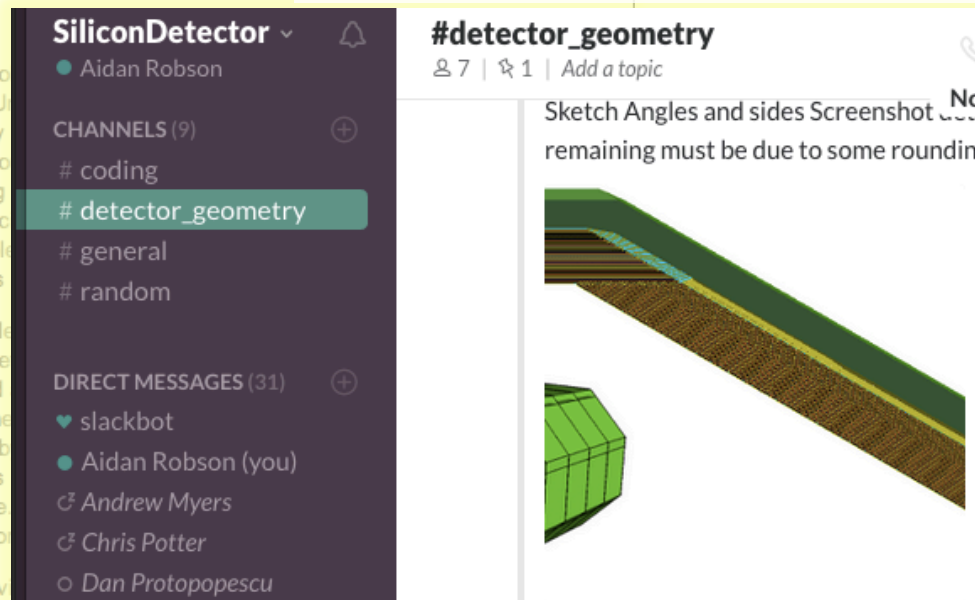
Participants of the 2016 SiD optimisation workshop at PNNL.

With LCWS in Morioka, students from the University of Cruz and University of SiD optimisation group dedicated to getting a framework. The Pacific event, and 20 people in WA, about 14 miles

While the ILC accelerator have a way to go before consortium decided reconstruction to the partially supported by disruptive, as users based infrastructure support for SiD's co

The benefits of having a common event data model like LCIO became obvious the old framework could easily be read in the new framework.

Work continuing via weekly meetings and collaborative tools e.g. slack channels



- ◆ SiD is a compact, capable detector
- ◆ Well-defined baseline that exceeds physics requirements
- ◆ Evolving: a lot of activity in detector R&D and in optimization
 - readout
 - sensors
 - structures
 - layout
 - simulation and reconstruction
- ◆ ...but limited effort available.

If you have ideas for the application of new technologies, software development, or new physics studies, we welcome to you consider joining the SiD Consortium!

